

HOSTAFORM®

POM copolymer

Easy flowing Injection molding type for precision molded parts and thin-walled molded parts with high rigidity, hardness and toughness; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. With UV Additives

Burning rate ISO 3795 and FMVSS 302 < 75 mm/min for a thickness more than 1 mm.

Ranges of applications: automotive engineering, precision engineering, electric and electronical industry, domestic appliances.

FMVSS = Federal Motor Vehicle Safety Standard (USA)

Product information

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Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469
Rheological properties			
Melt volume-flow rate	12	cm ³ /10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	2.0	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.8	%	ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus	2900	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	65	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	28	%	ISO 527-1/-2
Flexural modulus	2800	MPa	ISO 178
Tensile creep modulus, 1h	2500	MPa	ISO 899-1
Tensile creep modulus, 1000h	1300	MPa	ISO 899-1
Charpy impact strength, 23°C	200	kJ/m²	ISO 179/1eU
Charpy impact strength, -30°C	200	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	6.5	kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30°C	6	kJ/m²	ISO 179/1eA
Ball indentation hardness, H 358/30		MPa	ISO 2039-1
Poisson's ratio	0.37 ^[C]		
[C]: Calculated			
Thermal properties			
Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	106		ISO 75-1/-2
Coefficient of linear thermal expansion		E-6/K	ISO 11359-1/-2
(CLTE), parallel			
Thermal conductivity of melt	0.155	W/(m K)	ISO 22007-2
Specific heat capacity of melt		J/(kg K)	ISO 22007-4
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HOSTAFORM[®] C 13021 LS

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Electrical properties			
Relative permittivity, 100Hz	4		IEC 62631-2-1
Relative permittivity, 1MHz	4		IEC 62631-2-1
Dissipation factor, 100Hz		E-4	IEC 62631-2-1
Dissipation factor, 1MHz		E-4	IEC 62631-2-1
Volume resistivity		Ohm.m	IEC 62631-3-1
Surface resistivity		Ohm	IEC 62631-3-2
Electric strength		kV/mm	IEC 60243-1
Comparative tracking index	600		IEC 60112
Physical/Other properties			
Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65		Sim. to ISO 62
Density	1410	kg/m³	ISO 1183
Injection			
Drying Recommended	no		
Drying Temperature	100	°C	
Drying Time, Dehumidified Dryer	3 - 4	h	
Processing Moisture Content	≤0.2	%	
Melt Temperature Optimum	200	°C	
Min. melt temperature	190	°C	
Max. melt temperature	210	°C	
Screw tangential speed	≤0.3	m/s	
Mold Temperature Optimum	100	°C	
Min. mould temperature		°C	
Max. mould temperature	120		
Hold pressure range	60 - 120		
Back pressure		MPa	
Ejection temperature	140	°C	

Characteristics

Additives

Additional information

Processing Notes

Pre-Drying

Release agent

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

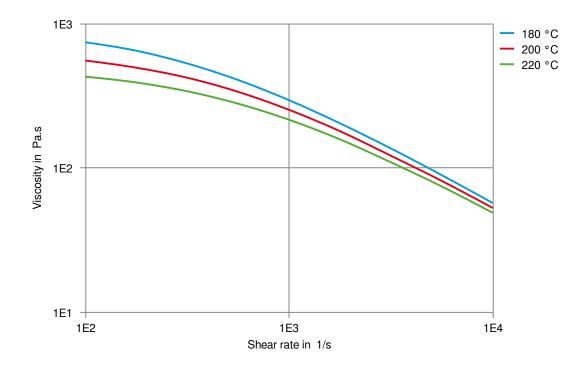
Storage

The product can then be stored in standard conditions until processed.

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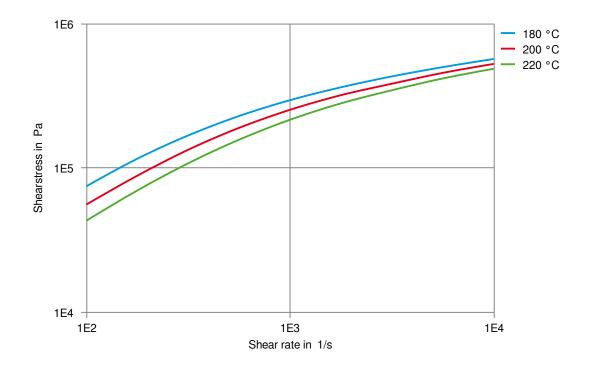


Viscosity-shear rate



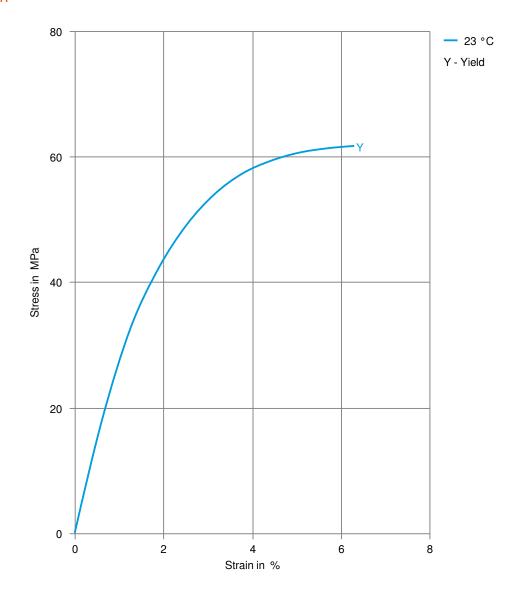


Shearstress-shear rate



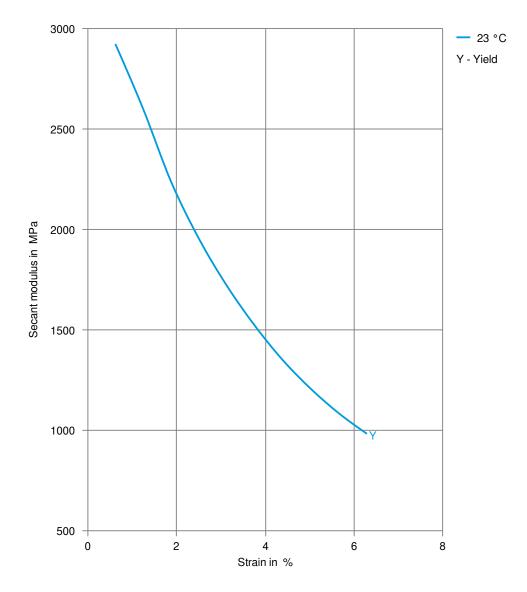


Stress-strain





Secant modulus-strain



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Page: 6 of 6

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